# PMP10600 Bill of Materials

| Designator | Quantity | Value | PartNumber | Manufacturer | Description | PackageReference |
|---|---|---|---|---|---|---|
| !PCB1 | 1 | | Printed Circuit Board | Any | Printed Circuit Board | |
| C1 | 1 | 100pF | GRM1885C2A101JA01D | MuRata | CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 0603 | 0603 |
| C2, C29, C31, C33 | 4 | 0.1uF | GRM155R61E104KA87D | MuRata | CAP, CERM, 0.1 µF, 25 V, +/- 10%, X5R, 0402 | 0402 |
| C3 | 1 | 0.1uF | GRM188R61E104KA01D | MuRata | CAP, CERM, 0.1uF, 25V, +/-10%, X5R, 0603 | 0603 |
| C4 | 1 | 10uF | GRM21BR61E106MA73 | MuRata | CAP, CERM, 10uF, 25V, +/-20%, X5R, 0805 | 0805 |
| C5 | 1 | 22uF | GRM21BR60J226ME39L | MuRata | CAP, CERM, 22uF, 6.3V, +/-20%, X5R, 0805 | 0805 |
| C6, C8 | 2 | 0.1uF | GRM155R71C104KA88D | MuRata | CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0402 | 0402 |
| C7 | 1 | 330uF | EEF-GX0D331R | Panasonic | CAP, TA, 330 µF, 2 V, +/- 20%, 0.003 ohm, SMD | SMD_7.3x1.9x4.3mm |
| C9 | 1 | 22uF | GRM31CR71A226KE15L | MuRata | CAP, CERM, 22 µF, 10 V, +/- 10%, X7R, 1206 | 1206 |
| C10, C18 | 2 | 68uF | 16TQC68MYF | Panasonic | CAP, TA, 68uF, 16V, +/-20%, 0.05 ohm, SMD | 7.3x2.0x4.3mm |
| C11, C19 | 2 | 47uF | GRM32ER61C476ME15L | MuRata | CAP, CERM, 47uF, 16V, +/-20%, X5R, 1210 | 1210 |
| C12, C20 | 2 | 3300pF | GRM155R71H332KA01D | MuRata | CAP, CERM, 3300pF, 50V, +/-10%, X7R, 0402 | 0402 |
| C13 | 1 | 220uF | EEFSX0G221ER | Panasonic | CAP, AL, 220uF, 4V, +/-20%, 9 ohm, SMD | 7.3x1.8x4.3mm |
| C14, C15, C16, C17, C22, C23, C24, C25, C26, C27 | 10 | 47uF | GRM32ER60J476ME20L | MuRata | CAP, CERM, 47uF, 6.3V, +/-20%, X5R, 1210 | 1210 |
| C21 | 1 | 330uF | EEFSX0E331ER | Panasonic | CAP, AL, 330 µF, 2.5 V, +/- 20%, 9 ohm, SMD | 7.3x1.8x4.3mm |
| C30, C32 | 2 | 10uF | GRM188R60J106ME47D | MuRata | CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0603 | 0603 |
| C34 | 1 | 4.7uF | GRM188R60J475KE19D | MuRata | CAP, CERM, 4.7 µF, 6.3 V, +/- 10%, X5R, 0603 | 0603 |
| C35 | 1 | 1uF | GRM155R61A105KE15D | MuRata | CAP, CERM, 1 µF, 10 V, +/- 10%, X5R, 0402 | 0402 |
| C36 | 1 | 2.2uF | GRM155R60J225ME15D | MuRata | CAP, CERM, 2.2 µF, 6.3 V, +/- 20%, X5R, 0402 | 0402 |
| D1 | 1 | 5.1V | BZT52C5V1T-7 | Diodes Inc. | Diode, Zener, 5.1V, 300mW, SOD-523 | SOD-523 |
| FID1, FID2, FID3 | 3 | | N/A | N/A | Fiducial mark. There is nothing to buy or mount. | Fiducial |
| H1, H2, H3, H4 | 4 | | SJ-5303 (CLEAR) | 3M | Bumpon, Hemisphere, 0.44 X 0.20, Clear | Transparent Bumpon |
| J1 | 1 | | PEC02SAAN | Sullins Connector Solutions | Header, 100mil, 2x1, Tin, TH | Header, 2 PIN, 100mil, Tin |
| J2, J3 | 2 | | ED120/2DS | On-Shore Technology | TERMINAL BLOCK 5.08MM VERT 2POS, TH | TERM_BLK, 2pos, 5.08mm |
| L1 | 1 | 10uH | XAL4040-103MEB | Coilcraft | Inductor, Shielded, Composite, 10uH, 3A, 0.084 ohm, SMD | 4.0x4.1x4.0mm |
| LBL1 | 1 | | THT-14-423-10 | Brady | Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll | PCB Label 0.650"H x 0.200"W |
| R1 | 1 | 68.1k | CRCW060368K1FKEA | Vishay-Dale | RES, 68.1k ohm, 1%, 0.1W, 0603 | 0603 |
| R2, R3, R5, R8 | 4 | 100k | CRCW0603100KJNEA | Vishay-Dale | RES, 100k ohm, 5%, 0.1W, 0603 | 0603 |
| R4 | 1 | 12.1k | CRCW060312K1FKEA | Vishay-Dale | RES, 12.1k ohm, 1%, 0.1W, 0603 | 0603 |
| R6 | 1 | 105k | RT0603BRD07105KL | Yageo America | RES, 105k ohm, 0.1%, 0.1W, 0603 | 0603 |
| R7 | 1 | 20.0k | RG1608P-203-B-T5 | Susumu Co Ltd | RES, 20.0k ohm, 0.1%, 0.1W, 0603 | 0603 |
| R9, R12 | 2 | 49.9 | CRCW060349R9FKEA | Vishay-Dale | RES, 49.9 ohm, 1%, 0.1W, 0603 | 0603 |
| R10 | 1 | 1.13k | CRCW06031K13FKEA | Vishay-Dale | RES, 1.13 k, 1%, 0.1 W, 0603 | 0603 |
| R11 | 1 | 324k | CRCW0603324KFKEA | Vishay-Dale | RES, 324 k, 1%, 0.1 W, 0603 | 0603 |
| R13 | 1 | 5.76k | CRCW06035K76FKEA | Vishay-Dale | RES, 5.76 k, 1%, 0.1 W, 0603 | 0603 |
| R14 | 1 | 261k | CRCW0603261KFKEA | Vishay-Dale | RES, 261k ohm, 1%, 0.1W, 0603 | 0603 |
| R15 | 1 | 21.5k | CRCW040221K5FKED | Vishay-Dale | RES, 21.5 k, 1%, 0.063 W, 0402 | 0402 |
| R16 | 1 | 1.50Meg | CRCW04021M50FKED | Vishay-Dale | RES, 1.50 M, 1%, 0.063 W, 0402 | 0402 |
| R17 | 1 | 178k | CRCW0402178KFKED | Vishay-Dale | RES, 178 k, 1%, 0.063 W, 0402 | 0402 |
| SH-J1 | 1 | 1x2 | 969102-0000-DA | 3M | Shunt, 100mil, Gold plated, Black | Shunt |
| TP1 | 1 | White | 5002 | Keystone | Test Point, Miniature, White, TH | White Miniature Testpoint |

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|---|---|---|---|---|---|---|
| TP2, TP4, TP8, TP10, TP11, TP14, TP15 | 7 | Red | 5010 | Keystone | Test Point, Multipurpose, Red, TH | Red Multipurpose Testpoint |
| TP3, TP5, TP9, TP12, TP13, TP16, TP17 | 7 | Black | 5011 | Keystone | Test Point, Multipurpose, Black, TH | Black Multipurpose Testpoint |
| TP6 | 1 | Red | 5000 | Keystone | Test Point, Miniature, Red, TH | Red Miniature Testpoint |
| TP7 | 1 | Black | 5001 | Keystone | Test Point, Miniature, Black, TH | Black Miniature Testpoint |
| U1 | 1 | | LM3880QMFE-1AA/NOPB | Texas Instruments | Power Sequencer, 6-pin SOT-23, Pb-Free | MF06A |
| U2 | 1 | | TPS560200DBV | Texas Instruments | 4.5V to 18V Input, 500mA Synchronous Step Down SWIFT Converter, DBV0005A | DBV0005A |
| U3 | 1 | | LP2998QMR/NOPB | Texas Instruments | DDR-I and DDR-II Termination Regulator, 8-pin PSOP, Pb-Free | MRA08A |
| U4, U5 | 2 | | LMZ31503RUQ | Texas Instruments | 3A SIMPLE SWITCHER Power Module with 4.5V-14.5V Input in QFN Package, RUQ0047A | RUQ0047A |
| U6 | 1 | | TPS73101DBV | Texas Instruments | Cap-Free, NMOS, 150mA Low Dropout Regulator with Reverse Current Protection, DBV0005A | DBV0005A |
| U7 | 1 | | TPS7A3501DRV | Texas Instruments | Low Noise, High PSRR 1A Active Filter, DRV0006A | DRV0006A |
| U8 | 1 | | LP2980AIM5-2.5/NOPB | Texas Instruments | Micropower 50 mA Ultra Low-Dropout Regulator, 5-pin SOT-23, Pb-Free | MF05A |
| U9 | 1 | | LP3991TL-1.2/NOPB | Texas Instruments | 300mA Linear Voltage Regulator for Digital Applications, 4-pin Micro SMD, Pb-Free | TLA04ZTA |

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